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(21) Application number: **02237713**

(71) Applicant: **MITSUBISHI ELECTRIC CORP**

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(72) Inventor: **SAWANO HIROSHI**

(54) SEMICONDUCTOR DEVICE

(57) Abstract:

PURPOSE: To reduce the size of a package by forming a chip wherein the circuit function of a semiconductor device is divided into two chips, and sealing said chips which are stacked in the same package.

CONSTITUTION: The title semiconductor device is formed by dividing a chip constituting a circuit into two chips, and sealing the divided chips which are stacked. Thereby a chip size is restrained and the defective rate can be decreased. Since the package size is reduced, the mounting area can be made small.

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